# Zibo Seno Electronic Engineering Co., Ltd.



# RS2001M - RS2007M 🚱 🏑

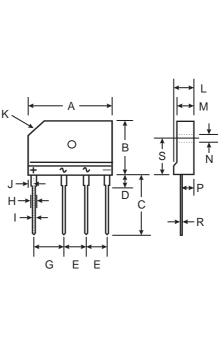
## 20A GLASS PASSIVATED BRIDGE RECTIFIER

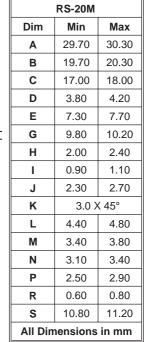
#### Features

- Glass Passivated Die Construction
- High Case Dielectric Strength of 1500V<sub>RMS</sub>
- Low Reverse Leakage Current
- Surge Overload Rating to 350A Peak
- Ideal for Printed Circuit Board Applications
- Plastic Material UL Flammability Classification 94V-0
- Lead Free:For RoHS / Lead Free Version

#### **Mechanical Data**

- Case: Molded Plastic
- Terminals: Plated Leads, Solderable per MIL-STD-202, Method 208
- Polarity: Molded on Body
- Mounting: Through Hole for #6 Screw
- Mounting Torque: 5.0 in-lbs Maximum
- Weight: 6.6 grams (approx)
- Marking: Type Number





## Maximum Ratings and Electrical Characteristics <sup>@</sup> T<sub>A</sub> = 25°C unless otherwise specified

Single phase, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	RS 2001M	RS 2002M	RS 2003M	RS 2004M	RS 2005M	RS 2006M	RS 2007M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Forward Rectified Output Current @ $T_C = 110^{\circ}C$	Ι <sub>Ο</sub>	20							Α
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave superimposed on rated load	IFSM	240						А	
Forward Voltage per element @ I <sub>F</sub> = 10A	VFM	1.05						V	
Peak Reverse Current@ $T_A = 25^{\circ}C$ at Rated DC Blocking Voltage@ $T_C = 125^{\circ}C$	I <sub>R</sub>	10 500						μA	
I <sup>2</sup> t Rating for Fusing (t < 8.3 ms) (Note 1)	l <sup>2</sup> t	240							A <sup>2</sup> s
Typical Total Capacitance per Element (Note 2)	Ст	60							pF
Typical Thermal Resistance Junction to Case (Note 3)	R <sub>θJC</sub>	0.8						°C/W	
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +150							°C

Notes: 1. Non-repetitive, for t > 1ms and < 8.3 ms.

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

3. Unit mounted on 300 x 300 x 1.6mm Cu plate heat sink.

4. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.

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